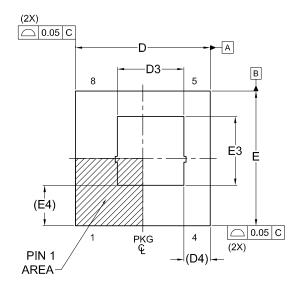
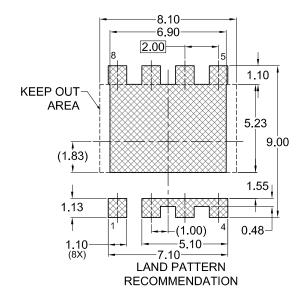




PQFN8 8X8, 2P CASE 483AQ **ISSUE B**

DATE 24 OCT 2022





TOP VIEW SEE DETAIL A

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

FRONT VIEW 0.10M C A B e1 .05(M) C е b (8X) (8X) -(L1) PIN #1 IDENT NOTES: e2 E5 E2 e3 (4X) E6 (z)(4X)D2 **BOTTOM VIEW**

| <u> </u> | | Å |
|----------|-----------------------|--------------|
| (A3) | A1_ | C SEATING |
| | DETAIL A SCALE: 2X | PLANE |

1. DIMENSIONING AND TOLERANCING PER ASME

- Y14.5M, 2009. 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
- SEATING PLANE IS DEFINED BY THE TERMINALS. "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- 6. IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.

| ЫМ | MILLIMETERS | | | |
|----|-------------|------|------|--|
| J | MIN. | NOM. | MAX. | |
| Α | 0.75 | 0.85 | 0.95 | |
| A1 | 0.00 | - | 0.05 | |
| A3 | 0.25 REF | | | |
| b | 0.90 | 1.00 | 1.10 | |
| D | 7.90 | 8.00 | 8.10 | |
| D2 | 6.80 | 6.90 | 7.00 | |
| D3 | 3.68 | 3.86 | 4.03 | |
| D4 | 1.56 REF | | | |
| E | 7.90 | 8.00 | 8.10 | |
| E2 | 5.13 | 5.23 | 5.33 | |
| E3 | 3.99 | 4.09 | 4.19 | |
| E4 | 2.41 REF | | | |
| E5 | 0.35 REF | | | |
| E6 | 0.60 REF | | | |
| е | 2.00 BSC | | | |
| e1 | 6.00 BSC | | | |
| e2 | 1.20 BSC | | | |
| e3 | 2.78 BSC | | | |
| k | 1.48 | 1.58 | 1.68 | |
| L | 0.50 | 0.60 | 0.70 | |
| L1 | 0.20 REF | | | |
| Z | 0.50 REF | | | |

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